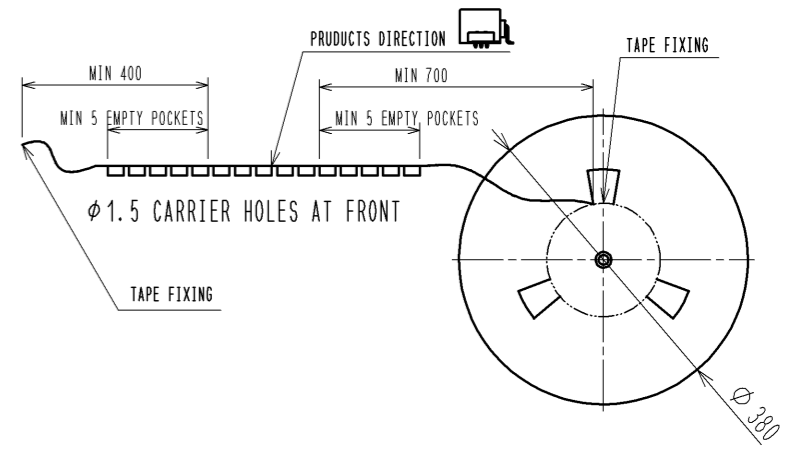
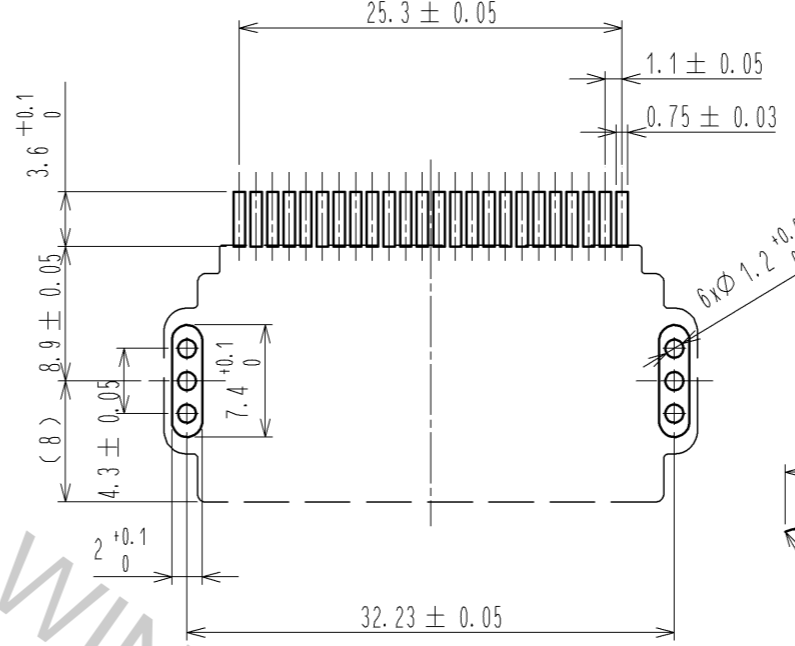
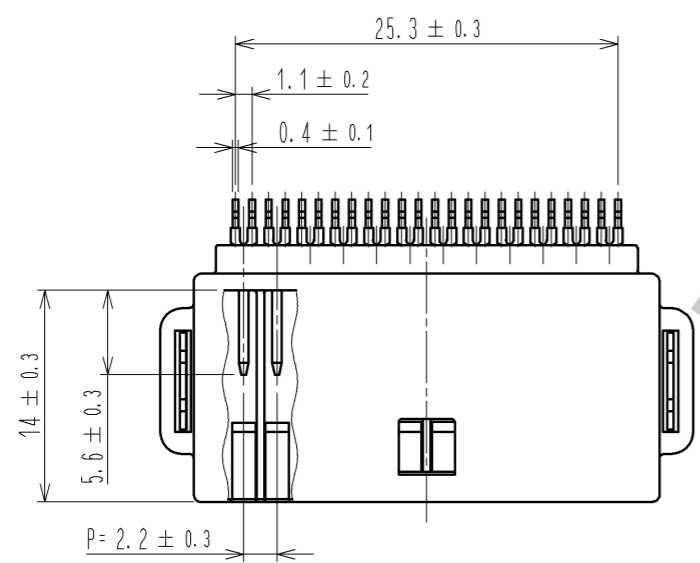
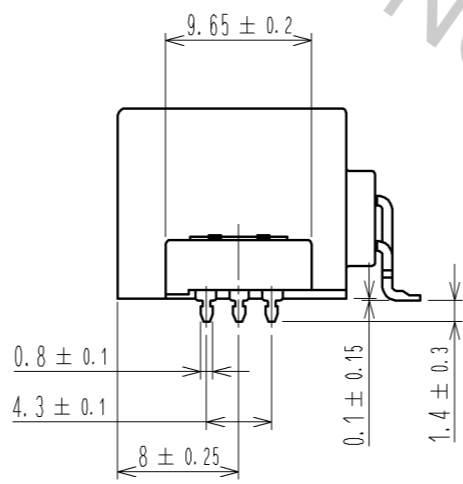
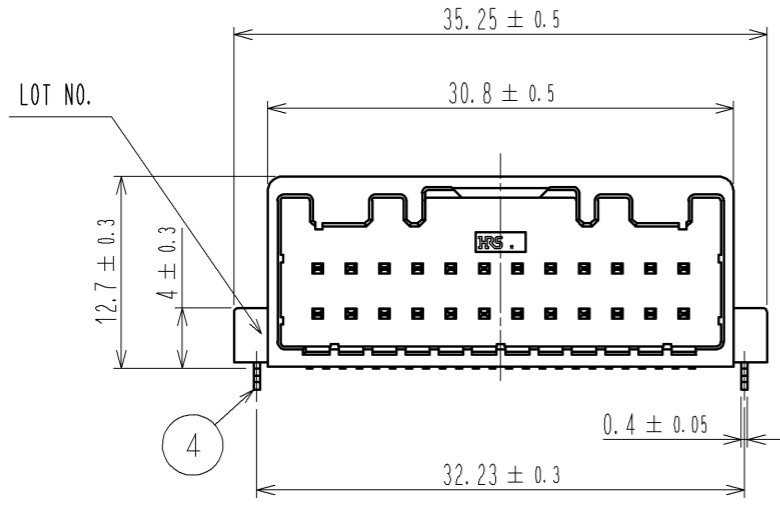


ELV, RoHS COMPLIANT

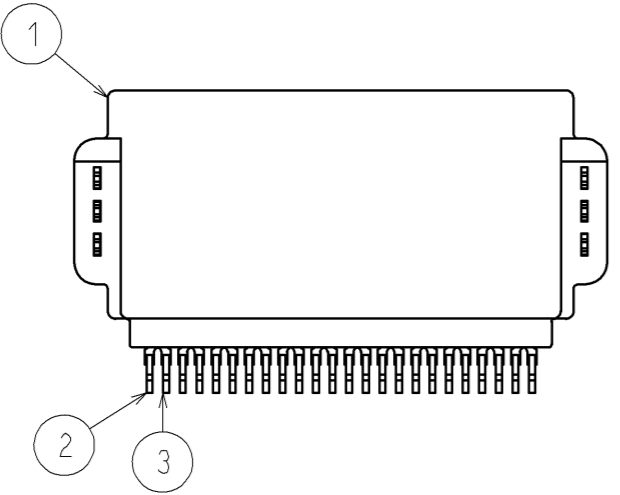
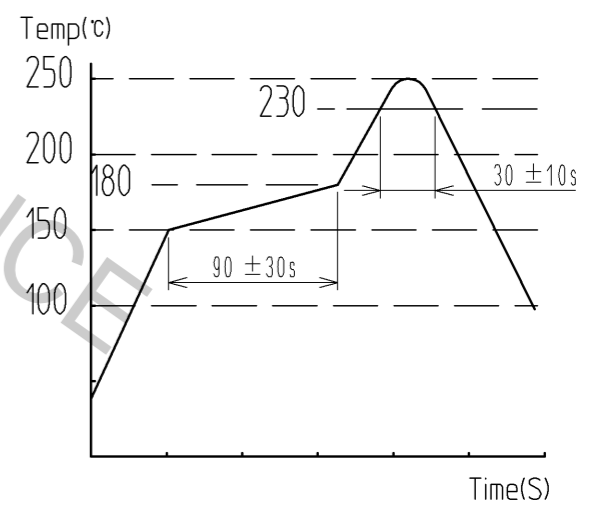


RECOMMENDED PC BOARD PATTERN



EMBOSS SPECULATION

- NOTE 1. RECOMMENDED TEMPERATURE PROFILE FOR REFLOW (REFER TO RIGHT FIG.)
 USED REFLOW SYSTEM : IR IN THE AIR OR NITROGEN
 NO. OF CYCLES : 2 MAX
 PEAK : 250°C
 OVER 230°C : 20~40s
 PREHEAT : 150~180°C 60~120s
2. TEMPERATURE FOR SOLDERING IRON : 280~300°C WITHIN 2s
3. CO-PLANARITY SHALL BE 0.1 MAX.
 4. PC BOARD THICKNESS=1.6.
 5. RECOMMENDED SOLDER THICKNESS=0.15



2	BRASS	TIN PLATED	T=0.64	4	BRASS	TIN PLATED	T=0.4		
1	PPS	LIGHT GRAY		3	BRASS	TIN PLATED	T=0.64		
NO.	MATERIAL	FINISH	REMARKS	NO.	MATERIAL	FINISH	REMARKS		
UNITS	mm	SCALE	2 : 1	COUNT	1	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
						DIS-T-003532	TY. SAKASHITA	TY. TAKAHASHI	13. 10. 01
HRS HIROSE ELECTRIC CO., LTD.		APPROVED	: KS. SATOH	07. 04. 25	DRAWING NO.		EDC3-166409-00		
		CHECKED	: AR. SHIRAI	07. 04. 19	PART NO.		GT25-24DP-2. 2H		
		DESIGNED	: TY. SAKASHITA	07. 04. 19	CODE NO.		CL775-0007-0-00		
		DRAWN	: TY. SAKASHITA	07. 04. 19					